

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|---|------------------|----------------------|-------------------------|------------------|
| 10/601,147 | 06/19/2003 | Lawrence C. Gunn III | LUX-P004 | 7226 |
| 20995 7 | 590 12/15/2005 | | EXAM | INER |
| KNOBBE MARTENS OLSON & BEAR LLP 2040 MAIN STREET FOURTEENTH FLOOR | | | CHIEM, DINH D | |
| | | | ART UNIT | PAPER NUMBER |
| | IRVINE, CA 92614 | | 2883 | |
| | | | DATE MAILED: 12/15/2009 | 5 |

Please find below and/or attached an Office communication concerning this application or proceeding.

| | | <i></i> |
|--|--|---|
| | Application No. | Applicant(s) |
| | 10/601,147 | GUNN ET AL. |
| Office Action Summary | Examiner | Art Unit |
| | Erin D. Chiem | 2883 |
| The MAILING DATE of this communication a Period for Reply | ppears on the cover sheet with the | correspondence address |
| A SHORTENED STATUTORY PERIOD FOR REF WHICHEVER IS LONGER, FROM THE MAILING - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period. - Failure to reply within the set or extended period for reply will, by stat Any reply received by the Office later than three months after the ma earned patent term adjustment. See 37 CFR 1.704(b). | DATE OF THIS COMMUNICATIO 1.136(a). In no event, however, may a reply be ti od will apply and will expire SIX (6) MONTHS fron ute, cause the application to become ABANDONI | N. mely filed the mailing date of this communication. ED (35 U.S.C. § 133). |
| Status | | |
| 1) Responsive to communication(s) filed on 28 2a) This action is FINAL. 2b) TI 3) Since this application is in condition for allow closed in accordance with the practice unde | nis action is non-final. vance except for formal matters, pr | |
| Disposition of Claims | | |
| 4) ☐ Claim(s) 1-14 and 16-40 is/are pending in the 4a) Of the above claim(s) is/are withd 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-14 and 16-40 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and Application Papers 9) ☐ The specification is objected to by the Examing 10) ☐ The drawing(s) filed on 19 June 2003 is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. | rawn from consideration. d/or election requirement. iner. a) □ accepted or b) ☒ objected to be drawing(s) be held in abeyance. Seection is required if the drawing(s) is of | ee 37 CFR 1.85(a). pjected to. See 37 CFR 1.121(d). |
| Priority under 35 U.S.C. § 119 | | |
| 12) Acknowledgment is made of a claim for forei a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the priority docume application from the International Bure * See the attached detailed Office action for a li | ents have been received. ents have been received in Applica rionty documents have been receive eau (PCT Rule 17.2(a)). | tion No red in this National Stage |
| Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date | 4) Interview Summar Paper No(s)/Mail [5) Notice of Informal 6) Other: | |

DETAILED ACTION

This office action is in response to the Request for Continuing Examination. Currently, claim 15 is canceled, claims 1, 2, 5-8, 16, 17, 20-23, 31, 32, and 35-39 are amended; claims 1-14 and 16-40 are pending.

Drawings

The Examiner reconsidered the amended subject matter in the independent claims and find that the Drawings are insufficient to support the newly amended claims. New corrected drawings in compliance with 37 CFR 1.121(d) are required in this application because Figure 2 and Figure 3 are inadequate. Applicant is advised to employ the services of a competent patent draftsperson outside the Office, as the U.S. Patent and Trademark Office no longer prepares new drawings. The corrected drawings are required in reply to the Office action to avoid abandonment of the application. The requirement for corrected drawings will not be held in abeyance.

The drawings are objected to under 37 CFR 1.83(a). The drawings must show every feature of the invention specified in the claims. Therefore, the following features must be shown or the feature(s) wavelength-demultiplexing device (claims 13 and 28) must be shown or the feature(s) canceled from the claim(s). No new matter should be entered.

Corrected drawing sheets in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. Any amended replacement drawing sheet should include all of the figures appearing on the immediate prior version of the sheet,

-+ I Init. 2002

even if only one figure is being amended. The figure or figure number of an amended drawing should not be labeled as "amended." If a drawing figure is to be canceled, the appropriate figure must be removed from the replacement sheet, and where necessary, the remaining figures must be renumbered and appropriate changes made to the brief description of the several views of the drawings for consistency. Additional replacement sheets may be necessary to show the renumbering of the remaining figures. Each drawing sheet submitted after the filing date of an application must be labeled in the top margin as either "Replacement Sheet" or "New Sheet" pursuant to 37 CFR 1.121(d). If the changes are not accepted by the examiner, the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

The drawings are objected to because claims 1, 16, 31, 32, 37, 38, and 39 claim that the array of optical grating couplers reside on the first substrate and the first substrate is oriented in a parallel plane above the second substrate; however, Figure 3 shows the grating coupler 303 resides on the lower substrate. Corrected drawing sheets in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. Any amended replacement drawing sheet should include all of the figures appearing on the immediate prior version of the sheet, even if only one figure is being amended. The figure or figure number of an amended drawing should not be labeled as "amended." If a drawing figure is to be canceled, the appropriate figure must be removed from the replacement sheet, and where necessary, the remaining figures must be renumbered and appropriate changes made to the brief description of the several views of the drawings for consistency. Additional replacement sheets may be necessary to show the renumbering of the remaining figures. Each drawing sheet submitted after

the filing date of an application must be labeled in the top margin as either "Replacement Sheet" or "New Sheet" pursuant to 37 CFR 1.121(d). If the changes are not accepted by the examiner, the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance. For the purpose of examination, the Examiner shall reverse the grating onto the second substrate.

Claim Objections

Claim 32 is objected to because of the following informalities: the recitations:

- the first of the array of optical devices
- the first of the array of optical grating couplers
- the last of the array of the optical devices
- the last of the array of optical grating couplers

lack antecedent basis. Appropriate correction is required. For purpose of examination, the Examiner shall interpret -the—as -a-.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Application/Control Number: 10/601,147

Art Unit: 2883

Claims 1-14 and 16-30 are rejected under 35 U.S.C. 102(e) as being anticipated by Tanguay, Jr. et al. (US Patent 5,568,574 Tanguay herein forth).

Tanguay teaches the limitation of independent claims 1 and 16 in Figure 3. The optical apparatus (10) comprised of an array of optical grating couplers (16a, 16b) fabricated on a second substrate; and an array of optical devices (30a, 30b) on a first substrate, the first and second substrates are oriented on two separate planes that are parallel to each other; wherein the first substrate is positioned above the second substrate such that the array of optical grating couplers is optically aligned to the array of optical devices, light propagating out of the second plane from the array of optical grating couplers (see arrows) and into the first plane to the array of optical devices and into the second plane to the array of optical grating couplers (see Fig. 4 for further details of the light paths).

Claims 2, 5-7, 14, 17, 20-22, 29, and 30: the mechanical attachment of the two substrates may be die-attach epoxy, optical cement, or flip-chip bonding techniques (col. 8, lines 58-59). The flip-chip bonding techniques require a metallic bump, which could be lead, gold or any suitable metal, formed between two conductive pads (38), as shown in Fig. 5 element 48b. Furthermore, in the art of optoelectronic device flip-chip bonding technique is also known as Controlled Collapse Chip Connection or C4.

Claims 3 and 18: the optical devices in Figure 3 are modulators (col. 8, line 64).

<u>Claims 4 and 19</u>: the first substrate is a hybrid integration of silicon-based processing electronics (col. 6, lines 38-39).

<u>Claims 8-11 and 23-26</u>: Tanguay teaches employing electronic drive circuitry associated with each modulator element is incorporated on a substrate, and modern electronic drive circuitry

routinely uses transistors to supply electrical signals to the devices. Regarding claims 11, and 26, these are product-by-process claims and they are not given patentable weight.

Claims 12 and 27 are routine practices in the optics art when one of ordinary skill such as Tanguay would design the for the optical mode field of the grating coupler and the optical device to match such that the optical signal would couple, a fundamental concept in optical transmission.

Claims 13 and 28 are taught by Tanguay in terms of the motivation for employing parallel chip-to-chip interconnections such that chip area is reduced and allow the method allows for multiple interconnection routing on the chip and multiplex and demultiplexing of each I/O port (col. 2, lines 30-33).

Claim 31 is taught by Tanguay in Fig. 3 and 5. The optical apparatus (10) comprised of an array of optical grating couplers (16a, 16b) fabricated on a second substrate; and an array of optical devices (30a, 30b) on a first substrate, the first and second substrates are oriented on two separate planes that are parallel to each other; wherein the first substrate is positioned above the second substrate such that the array of optical grating couplers is optically aligned to the array of optical devices. Wherein the silicon-based integrated chip is mechanically fixed in optical alignment by flip-chip bonding.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 32-36 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tanguay in view of Kamon et al. (US 5,285,258 Kamon herein forth) and Giboney et al. (US 6,318,909 B1 Giboney herein forth).

Tanguay teaches passively aligning the grating coupler array on one substrate and the optical devices array on another substrate employing mask alignment (col. 15, line 1). Although Tanguay does not explicitly teaches aligning the first element of the optical device array to the first element of the grating coupler array and on forth until the last element in both arrays are aligned, but this limitation is obviate by the end result of the alignment shown in Fig. 3-5.

However, Tanguay does not explicitly teach forming the alignment mark on the second substrate and employ vision system with pattern recognition for automated alignment. Tanguay does not explicitly teach using a plurality of mask alignment marks on a plurality of masks used to fabricate an array of optical devices for alignment.

Kamon teaches that in the actual procedure for aligning stacked wafers the process involves detecting the alignment marks, and aligning mask marks to the alignment marks, commonly these marks are gratings, which are previously formed on a semiconductor wafer at predetermined positions (col. 1, lines 16-22) for the purpose of detecting the light intensity reflected from the gratings thus determining the best alignment based on the greatest intensity light reflected from the gratings.

However, Kamon does not teach using a vision system with pattern recognition for automated alignment.

Giboney teaches pattern recognition as a method employed an automatic aligning process for optical devices and the aligning members to position (col. 13, line 67 – col. 14, line 1 – 7). Alternatively, Giboney discloses 2 other aligning methods for alignment by (1) sending optical signals to the end of the fiber optic ribbon from the alignment connector, and determine the best signal-to-noise ratio generated by the optic device while the position of the optical device is optimized (col. 14, line23 – 30). (2) Another method is send electrical signals to the transmitting elements via the electrical connector to cause the transmitting elements to generate optical signals. The optical signals at the end of the fiber optic ribbon remote from the alignment connector are monitored, and the position of the assembly relative to the device package is manipulated until the optical signals have a maximum signal-to-noise ratio, or some other indication of an optimal alignment of the assembly is obtained col. 14, line 11 – 23). Giboney's method of automated alignment is for the purpose of aligning device arrays wherein passive alignment proved to be less accurate and more labor intensive.

Since Tanguay, Kamon, and Giboney are all from the same field of endeavor, the purpose disclosed by Kamon and Giboney would have been recognized in the pertinent art of Tanguay.

It would have been obvious at the time the invention was made to a person having ordinary skill in the art to align two arrays of devices such as grating couplings and optical devices, as taught by Tanguay, to employ photolithography to alignment marks in the form of gratings onto one of the two substrate of Tanguay's device dependent on the location of the optical source and photodetector. And then to apply one of two methods taught by Giboney to detect light intensity reflected from the alignment marks to determine the best alignment based on the greatest intensity of reflected light from the alignment marks. The motivation for

Application/Control Number: 10/601,147

Art Unit: 2883

employing automated alignment method is for its accuracy in aligning two arrays of devices and unlike passive alignment that is more labor intensive.

Claims 37-40 rejected under 35 U.S.C. 103(a) as being unpatentable over Tanguay in view of the Specification.

Tanguay teaches the flip-chip structure wherein an array of grating couplers formed on a semiconductor substrate and an array of optical devices, such as modulators and semiconductor diode lasers, formed on another semiconductor substrates and the two substrates are interconnected through flip-chip bonding. Tanguay teaches an integrated optoelectronic upper substrate to provide electronic circuitry control for any optical devices, such as the modulators and the semiconductor diode laser, and the lower substrate comprises the array of grating couplers on a planar waveguide. And Tanguay further teaches the instant interconnection provides easy coupling of the I/O ports to multiplexer and demultiplexer. Finally, in reviewing the Tanguay's reference in its entirety, Tanguay teaches how the flip-chip structure operates integrally as a device.

However, Tanguay does not explicitly teach the array of optical devices comprising photodetectors (claim 37) light splitting planar waveguide device.

The Specification, claims 3 and 18 further defines the array of optical devices is comprised of any elements from the list including VCSELs, laser, detectors, surface emitting laser, light emitting diodes, super luminescent diodes, modulators, filters, fibers, fiber components, lenses diffractive lenses, grating couplers, optical amplifiers, mirrors, or resonant cavities. The Specification, Background of the Invention, Summary of the Invention, and

Detailed Description is silent on how the flip-chip structure is critically different when employ any one of the above devices into the array of optical devices.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to employ any of the devices in the list above in place of the modulators and the semiconductor diode lasers, as taught by Tanguay, since it has been held that rearranging parts of an invention involves only routine skill in the art. In re Japikse, 86 USPQ 70. It is respectfully noted that applicant has not disclosed any criticality in the replacement of the optical devices in the list above in applicant's Specification. It is further noted that Tanguay does not specifically limit the optical devices to be only modulators and semiconductor laser diodes. Examiner's contention of this obvious choice in design can be overcome if applicant establishes the critical and significant differences in the flip-chip structure as claimed. No new matter should be entered.

Response to Arguments

Applicant's arguments with respect to claims 1-14 and 16-40 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Erin D. Chiem whose telephone number is (571) 272-3102. The examiner can normally be reached on Monday - Thursday 9AM - 5PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Frank G. Font can be reached on (571) 272-2415. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Erin D Chiem Examiner Art Unit 2883

Frank G. Font Supervisory Primary Examiner

Technology Center 2800

Frank & Fort